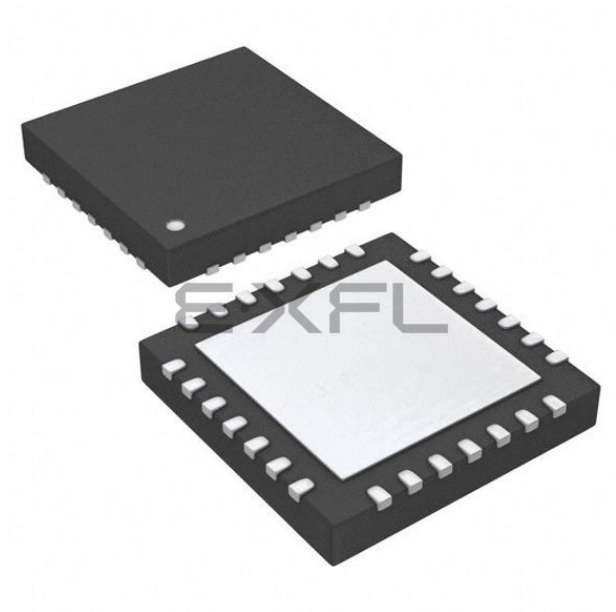
Microchip Technology - DSPIC33FJ12MC202T-I/ML Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I²C, IrDA, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, Motor Control PWM, QEI, POR, PWM, WDT
Number of I/O	21
Program Memory Size	12KB (12K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj12mc202t-i-ml

3.4 CPU Control Registers

REGISTER 3-1: SR: CPU STATUS REGISTER

R-0	R-0	R/C-0	R/C-0	R-0	R/C-0	R -0	R/W-0
OA	OB	SA(1)	SB(1)	OAB	SAB	DA	DC
bit 15							bit 8

R/W-0(2)	R/W-0(3)	R/W-0(3)	R-0	R/W-0	R/W-0	R/W-0	R/W-0
IPL<2:0>(2)			RA	N	OV	Z	C
bit 7							bit 0

Legend:		
C = Clear only bit	R = Readable bit	U = Unimplemented bit, read as '0'
S = Set only bit	W = Writable bit	-n = Value at POR
'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **OA:** Accumulator A Overflow Status bit
1 = Accumulator A overflowed
0 = Accumulator A has not overflowed

bit 14 **OB:** Accumulator B Overflow Status bit
1 = Accumulator B overflowed
0 = Accumulator B has not overflowed

bit 13 **SA:** Accumulator A Saturation 'Sticky' Status bit(1)
1 = Accumulator A is saturated or has been saturated at some time
0 = Accumulator A is not saturated

bit 12 **SB:** Accumulator B Saturation 'Sticky' Status bit(1)
1 = Accumulator B is saturated or has been saturated at some time
0 = Accumulator B is not saturated

bit 11 **OAB:** OA || OB Combined Accumulator Overflow Status bit
1 = Accumulators A or B have overflowed
0 = Neither Accumulators A or B have overflowed

bit 10 **SAB:** SA || SB Combined Accumulator 'Sticky' Status bit
1 = Accumulators A or B are saturated or have been saturated at some time in the past
0 = Neither Accumulator A or B are saturated
This bit may be read or cleared (not set). *Clearing this bit will clear SA and SB*.

bit 9 **DA:** DO Loop Active bit
1 = DO loop in progress
0 = DO loop not in progress

bit 8 **DC:** MCU ALU Half Carry/$\overline{\text{Borrow}}$ bit
1 = A carry-out from the 4th low-order bit (for byte-sized data) or 8th low-order bit (for word-sized data) of the result occurred
0 = No carry-out from the 4th low-order bit (for byte-sized data) or 8th low-order bit (for word-sized data) of the result occurred

Note 1: This bit can be read or cleared (not set).
2: The IPL<2:0> bits are concatenated with the IPL<3> bit (CORCON<3>) to form the CPU Interrupt Priority Level. The value in parentheses indicates the IPL if IPL<3> = 1. User interrupts are disabled when IPL<3> = 1.
3: The IPL<2:0> Status bits are read-only when NSTDIS = 1 (INTCON1<15>).

3.5 Arithmetic Logic Unit (ALU)

The dsPIC33FJ12MC201/202 ALU is 16 bits wide and is capable of addition, subtraction, bit shifts, and logic operations. Unless otherwise mentioned, arithmetic operations are 2's complement in nature. Depending on the operation, the ALU can affect the values of the Carry (C), Zero (Z), Negative (N), Overflow (OV), and Digit Carry (DC) Status bits in the SR register. The C and DC Status bits operate as Borrow and Digit Borrow bits, respectively, for subtraction operations.

The ALU can perform 8-bit or 16-bit operations, depending on the mode of the instruction that is used. Data for the ALU operation can come from the W register array or data memory, depending on the addressing mode of the instruction. Likewise, output data from the ALU can be written to the W register array or a data memory location.

Refer to the *"16-bit MCU and DSC Programmer's Reference Manual"* (DS70157) for information on the SR bits affected by each instruction.

The dsPIC33FJ12MC201/202 CPU incorporates hardware support for both multiplication and division. This includes a dedicated hardware multiplier and support hardware for 16-bit-divisor division.

3.5.1 MULTIPLIER

Using the high-speed 17-bit x 17-bit multiplier of the DSP engine, the ALU supports unsigned, signed or mixed-sign operation in several MCU multiplication modes:

- 16-bit x 16-bit signed
- 16-bit x 16-bit unsigned
- 16-bit signed x 5-bit (literal) unsigned
- 16-bit unsigned x 16-bit unsigned
- 16-bit unsigned x 5-bit (literal) unsigned
- 16-bit unsigned x 16-bit signed
- 8-bit unsigned x 8-bit unsigned

3.5.2 DIVIDER

The divide block supports 32-bit/16-bit and 16-bit/16-bit signed and unsigned integer divide operations with the following data sizes:

1. 32-bit signed/16-bit signed divide
2. 32-bit unsigned/16-bit unsigned divide
3. 16-bit signed/16-bit signed divide
4. 16-bit unsigned/16-bit unsigned divide

The quotient for all divide instructions ends up in W0 and the remainder in W1. 16-bit signed and unsigned DIV instructions can specify any W register for both the 16-bit divisor (Wn) and any W register (aligned) pair (W(m + 1):Wm) for the 32-bit dividend. The divide algorithm takes one cycle per bit of divisor, so both 32-bit/16-bit and 16-bit/16-bit instructions take the same number of cycles to execute.

3.6 DSP Engine

The DSP engine consists of a high-speed 17-bit x 17-bit multiplier, a barrel shifter and a 40-bit adder/subtracter (with two target accumulators, round and saturation logic).

The dsPIC33FJ12MC201/202 is a single-cycle instruction flow architecture; therefore, concurrent operation of the DSP engine with MCU instruction flow is not possible. However, some MCU ALU and DSP engine resources can be used concurrently by the same instruction (e.g., ED, EDAC).

The DSP engine can also perform inherent accumulator-to-accumulator operations that require no additional data. These instructions are ADD, SUB, and NEG.

The DSP engine has options selected through bits in the CPU Core Control register (CORCON), as listed below:

- Fractional or integer DSP multiply (IF)
- Signed or unsigned DSP multiply (US)
- Conventional or convergent rounding (RND)
- Automatic saturation on/off for ACCA (SATA)
- Automatic saturation on/off for ACCB (SATB)
- Automatic saturation on/off for writes to data memory (SATDW)
- Accumulator Saturation mode selection (ACCSAT)

A block diagram of the DSP engine is shown in Figure 3-3.

TABLE 3-1: DSP INSTRUCTIONS SUMMARY

Instruction	Algebraic Operation	ACC Write Back
CLR	$A = 0$	Yes
ED	$A = (x - y)^2$	No
EDAC	$A = A + (x - y)^2$	No
MAC	$A = A + (x * y)$	Yes
MAC	$A = A + x^2$	No
MOVSAC	No change in A	Yes
MPY	$A = x * y$	No
MPY	$A = x^2$	No
MPY.N	$A = -x * y$	No
MSC	$A = A - x * y$	Yes

5.0 FLASH PROGRAM MEMORY

Note 1: This data sheet summarizes the features of the dsPIC33FJ12MC201/202 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 5. "Flash Programming"** (DS70191) of the *"dsPIC33F/PIC24H Family Reference Manual"*, which is available from the Microchip website (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33FJ12MC201/202 devices contain internal Flash program memory for storing and executing application code. The memory is readable, writable, and erasable during normal operation over the entire VDD range.

Flash memory can be programmed in two ways:

- In-Circuit Serial Programming™ (ICSP™) programming capability
- Run-Time Self-Programming (RTSP)

ICSP allows a dsPIC33FJ12MC201/202 device to be serially programmed while in the end application circuit. This is done with two lines for programming clock and programming data (one of the alternate programming pin pairs: PGECx/PGEDx), and three other lines for power (VDD), ground (VSS) and Master Clear ($\overline{MCLR}$). This allows users to manufacture boards with unprogrammed devices, and then program the digital signal controller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

RTSP is accomplished using TBLRD (table read) and TBLWT (table write) instructions. With RTSP, the user application can write program memory data either in blocks or 'rows' of 64 instructions (192 bytes) or a single program memory word, and erase program memory in blocks or 'pages' of 512 instructions (1536 bytes).

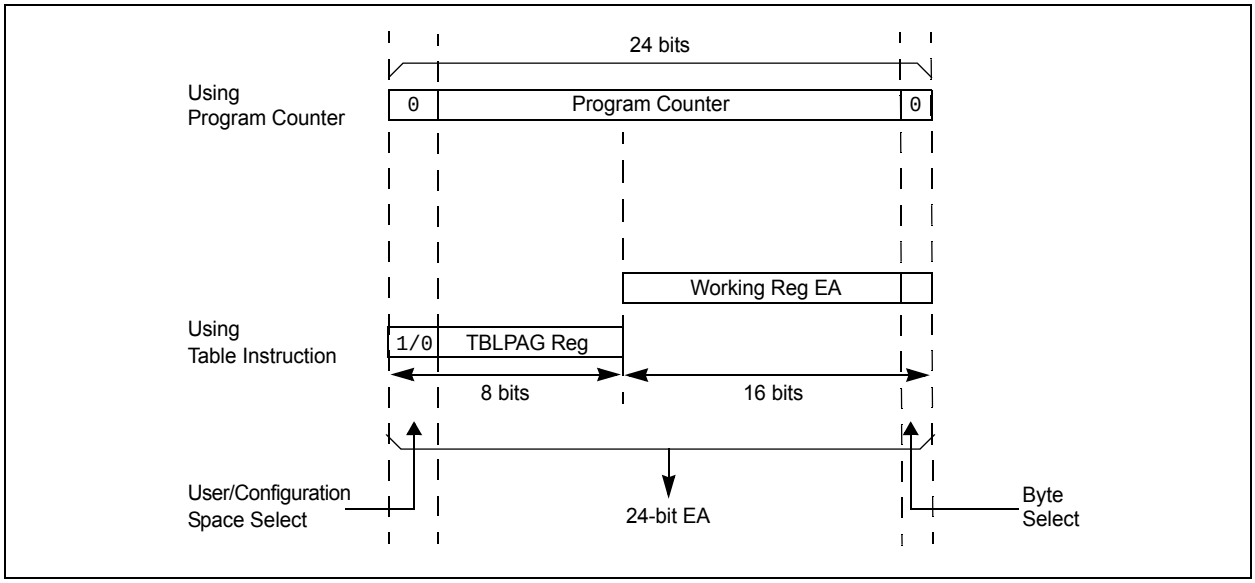
5.1 Table Instructions and Flash Programming

Regardless of the method used, all programming of Flash memory is done with the table-read and table-write instructions. These allow direct read and write access to the program memory space from the data memory while the device is in normal operating mode. The 24-bit target address in the program memory is formed using bits <7:0> of the TBLPAG register and the Effective Address (EA) from a W register specified in the table instruction, as shown in Figure 5-1.

The TBLRDL and the TBLWTL instructions are used to read or write to bits <15:0> of program memory. TBLRDL and TBLWTL can access program memory in both Word and Byte modes.

The TBLRDH and TBLWTH instructions are used to read or write to bits <23:16> of program memory. TBLRDH and TBLWTH can also access program memory in Word or Byte mode.

FIGURE 5-1: ADDRESSING FOR TABLE REGISTERS



EXAMPLE 5-2: LOADING THE WRITE BUFFERS

```
; Set up NVMCON for row programming operations
       MOV     #0x4001, W0               ;
       MOV     W0, NVMCON                ; Initialize NVMCON
; Set up a pointer to the first program memory location to be written
; program memory selected, and writes enabled
       MOV     #0x0000, W0               ;
       MOV     W0, TBLPAG                ; Initialize PM Page Boundary SFR
       MOV     #0x6000, W0               ; An example program memory address
; Perform the TBLWT instructions to write the latches
; 0th_program_word
       MOV     #LOW_WORD_0, W2           ;
       MOV     #HIGH_BYTE_0, W3          ;
       TBLWTL  W2, [W0]                  ; Write PM low word into program latch
       TBLWTH  W3, [W0++]                ; Write PM high byte into program latch
; 1st_program_word
       MOV     #LOW_WORD_1, W2           ;
       MOV     #HIGH_BYTE_1, W3          ;
       TBLWTL  W2, [W0]                  ; Write PM low word into program latch
       TBLWTH  W3, [W0++]                ; Write PM high byte into program latch
;  2nd_program_word
       MOV     #LOW_WORD_2, W2           ;
       MOV     #HIGH_BYTE_2, W3          ;
       TBLWTL  W2, [W0]                  ; Write PM low word into program latch
       TBLWTH  W3, [W0++]                ; Write PM high byte into program latch
       •
       •
       •
; 63rd_program_word
       MOV     #LOW_WORD_31, W2          ;
       MOV     #HIGH_BYTE_31, W3         ;
       TBLWTL  W2, [W0]                  ; Write PM low word into program latch
       TBLWTH  W3, [W0++]                ; Write PM high byte into program latch
```

EXAMPLE 5-3: INITIATING A PROGRAMMING SEQUENCE

```
       DISI    #5                        ; Block all interrupts with priority <7
                                         ; for next 5 instructions
       MOV     #0x55, W0
       MOV     W0, NVMKEY                ; Write the 55 key
       MOV     #0xAA, W1                 ;
       MOV     W1, NVMKEY                ; Write the AA key
       BSET    NVMCON, #WR               ; Start the erase sequence
       NOP                               ; Insert two NOPs after the
       NOP                               ; erase command is asserted
```

REGISTER 7-9: IEC0: INTERRUPT ENABLE CONTROL REGISTER 0 (CONTINUED)

bit 1 **IC1IE:** Input Capture Channel 1 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 0 **INT0IE:** External Interrupt 0 Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

REGISTER 7-19: IPC7: INTERRUPT PRIORITY CONTROL REGISTER 7

U-0	U-1	U-0	U-0	U-0	U-1	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—	INT2IP<2:0>			—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-7 **Unimplemented:** Read as ‘0’

bit 6-4 **INT2IP<2:0>:** External Interrupt 2 Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 3-0 **Unimplemented:** Read as ‘0’

TABLE 8-1: CONFIGURATION BIT VALUES FOR CLOCK SELECTION

Oscillator Mode	Oscillator Source	POSCMD<1:0>	FNOSC<2:0>	Note
Fast RC Oscillator with Divide-by-N (FRCDIVN)	Internal	xx	111	**1, 2**
Fast RC Oscillator with Divide-by-16 (FRCDIV16)	Internal	xx	110	**1**
Low-Power RC Oscillator (LPRC)	Internal	xx	101	**1**
Secondary (Timer1) Oscillator (SOSC)	Secondary	xx	100	**1**
Primary Oscillator (HS) with PLL (HSPLL)	Primary	10	011	**—**
Primary Oscillator (XT) with PLL (XTPLL)	Primary	01	011	**—**
Primary Oscillator (EC) with PLL (ECPLL)	Primary	00	011	**1**
Primary Oscillator (HS)	Primary	10	010	**—**
Primary Oscillator (XT)	Primary	01	010	**—**
Primary Oscillator (EC)	Primary	00	010	**1**
Fast RC Oscillator with PLL (FRCPLL)	Internal	xx	001	**1**
Fast RC Oscillator (FRC)	Internal	xx	000	**1**

Note 1: OSC2 pin function is determined by the OSCIOFNC Configuration bit.

2: This is the default oscillator mode for an unprogrammed (erased) device.

10.0 I/O PORTS

Note 1: This data sheet summarizes the features of the dsPIC33FJ12MC201/202 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 10. "I/O Ports"** (DS70193) of the *"dsPIC33F/PIC24H Family Reference Manual"*, which is available from the Microchip website (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

All of the device pins (except VDD, VSS, $\overline{\text{MCLR}}$, and OSC1/CLKI) are shared among the peripherals and the parallel I/O ports. All I/O input ports feature Schmitt Trigger inputs for improved noise immunity.

10.1 Parallel I/O (PIO) Ports

Generally a parallel I/O port that shares a pin with a peripheral is subservient to the peripheral. The peripheral's output buffer data and control signals are provided to a pair of multiplexers. The multiplexers select whether the peripheral or the associated port has ownership of the output data and control signals of the I/O pin. The logic also prevents "loop through," in which a port's digital output can drive the input of a peripheral that shares the same pin. Figure 10-1 shows how ports are shared with other peripherals and the associated I/O pin to which they are connected.

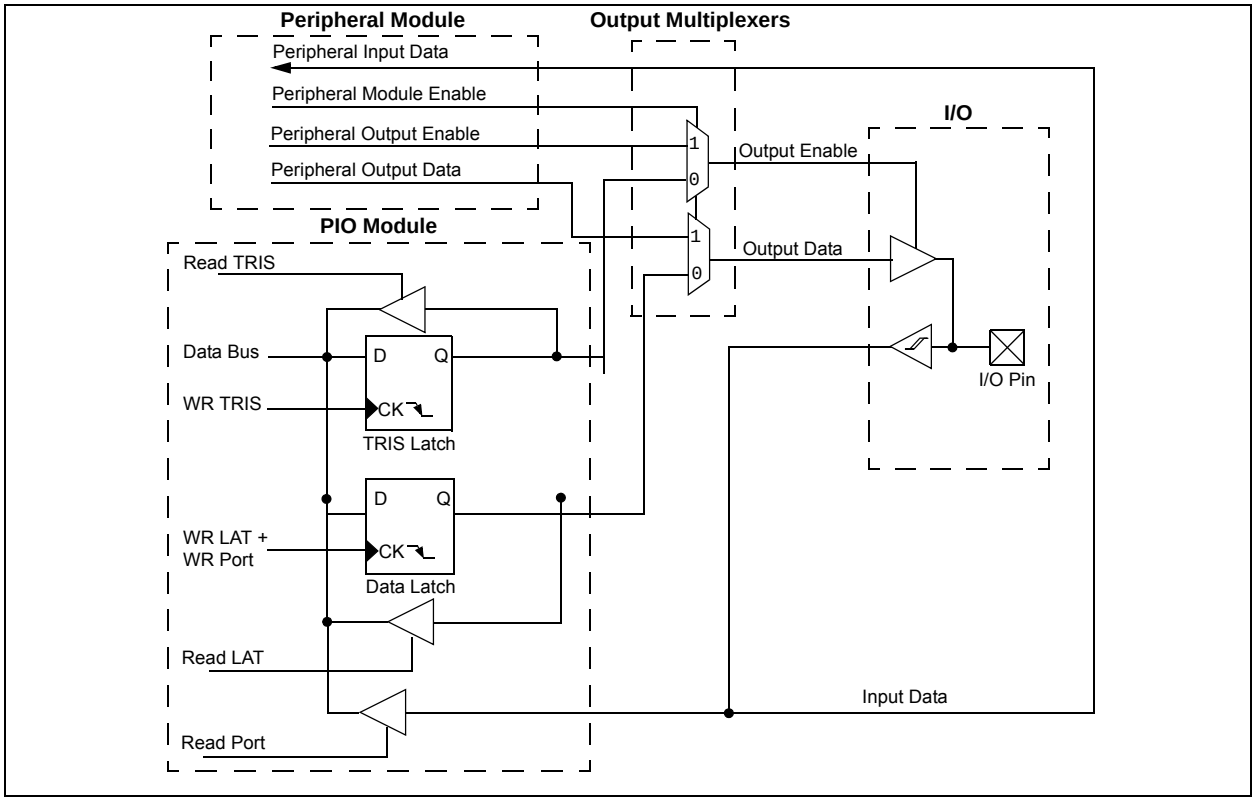
When a peripheral is enabled and the peripheral is actively driving an associated pin, the use of the pin as a general purpose output pin is disabled. The I/O pin can be read, but the output driver for the parallel port bit is disabled. If a peripheral is enabled, but the peripheral is not actively driving a pin, that pin can be driven by a port.

All port pins have three registers directly associated with their operation as digital I/O. The data direction register (TRISx) determines whether the pin is an input or an output. If the data direction bit is a '1', the pin is an input. All port pins are defined as inputs after a Reset. Reads from the latch (LATx) read the latch. Writes to the latch write the latch. Reads from the port (PORTx) read the port pins, while writes to the port pins write the latch.

Any bit and its associated data and control registers that are not valid for a particular device will be disabled. This means the corresponding LATx and TRISx registers and the port pin will read as zeros.

When a pin is shared with another peripheral or function that is defined as an input only, it is nevertheless regarded as a dedicated port because there is no other competing source of outputs.

FIGURE 10-1: BLOCK DIAGRAM OF A TYPICAL SHARED PORT STRUCTURE



10.4 Peripheral Pin Select

Peripheral pin select configuration enables peripheral set selection and placement on a wide range of I/O pins. By increasing the pinout options available on a particular device, programmers can better tailor the microcontroller to their entire application, rather than trimming the application to fit the device.

The peripheral pin select configuration feature operates over a fixed subset of digital I/O pins. Programmers can independently map the input and/or output of most digital peripherals to any one of these I/O pins. Peripheral pin select is performed in software, and generally does not require the device to be reprogrammed. Hardware safeguards are included that prevent accidental or spurious changes to the peripheral mapping, once it has been established.

10.4.1 AVAILABLE PINS

The peripheral pin select feature is used with a range of up to 16 pins. The number of available pins depends on the particular device and its pin count. Pins that support the peripheral pin select feature include the designation “RPn” in their full pin designation, where “RP” designates a remappable peripheral and “n” is the remappable pin number.

10.4.2 CONTROLLING PERIPHERAL PIN SELECT

Peripheral pin select features are controlled through two sets of special function registers: one to map peripheral inputs, and one to map outputs. Because they are separately controlled, a particular peripheral’s input and output (if the peripheral has both) can be placed on any selectable function pin without constraint.

The association of a peripheral to a peripheral selectable pin is handled in two different ways, depending on whether an input or output is being mapped.

10.4.2.1 Input Mapping

The inputs of the peripheral pin select options are mapped on the basis of the peripheral. A control register associated with a peripheral dictates the pin it will be mapped to. The RPINRx registers are used to configure peripheral input mapping (see Register 10-1 through Register 10-13). Each register contains sets of 5-bit fields, with each set associated with one of the remappable peripherals. Programming a given peripheral’s bit field with an appropriate 5-bit value maps the RPn pin with that value to that peripheral. For any given device, the valid range of values for any bit field corresponds to the maximum number of peripheral pin selections supported by the device.

Figure 10-2 Illustrates remappable pin selection for U1RX input.

Note:	For input mapping only, the Peripheral Pin Select (PPS) functionality does not have priority over the TRISx settings. Therefore, when configuring the RPx pin for input, the corresponding bit in the TRISx register must also be configured for input (i.e., set to ‘1’).

FIGURE 10-2: REMAPPABLE MUX INPUT FOR U1RX

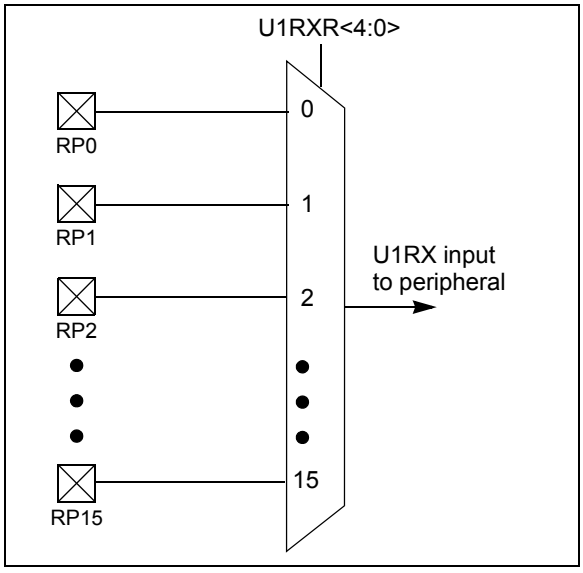


TABLE 10-2: OUTPUT SELECTION FOR REMAPPABLE PIN (RPn)

Function	RPnR<4:0>	Output Name
NULL	00000	RPn tied to default port pin
U1TX	00011	RPn tied to UART1 Transmit
$\overline{\text{U1RTS}}$	00100	RPn tied to UART1 Ready To Send
SDO1	00111	RPn tied to SPI1 Data Output
SCK1OUT	01000	RPn tied to SPI1 Clock Output
SS1OUT	01001	RPn tied to SPI1 Slave Select Output
OC1	10010	RPn tied to Output Compare 1
OC2	10011	RPn tied to Output Compare 2
UPDN	11010	RPn tied to QEI direction (UPDN) status

10.4.3 CONTROLLING CONFIGURATION CHANGES

Because peripheral remapping can be changed during run time, some restrictions on peripheral remapping are needed to prevent accidental configuration changes. dsPIC33FJ12MC201/202 devices include three features to prevent alterations to the peripheral map:

- Control register lock sequence
- Continuous state monitoring
- Configuration bit pin select lock

10.4.3.1 Control Register Lock

Under normal operation, writes to the RPINRx and RPORx registers are not allowed. Attempted writes appear to execute normally, but the contents of the registers remain unchanged. To change these registers, they must be unlocked in hardware. The register lock is controlled by the IOLOCK bit (OSCCON<6>). Setting IOLOCK prevents writes to the control registers; clearing IOLOCK allows writes.

To set or clear IOLOCK, a specific command sequence must be executed:

1. Write 0x46 to OSCCON<7:0>.
2. Write 0x57 to OSCCON<7:0>.
3. Clear (or set) IOLOCK as a single operation.

Note: MPLAB® C30 provides built-in C language functions for unlocking the OSCCON register:

```
__builtin_write_OSCCONL(value)
__builtin_write_OSCCONH(value)
```

See MPLAB IDE Help for more information.

Unlike the similar sequence with the oscillator's LOCK bit, IOLOCK remains in one state until changed. This allows all of the peripheral pin selects to be configured with a single unlock sequence followed by an update to all control registers, then locked with a second lock sequence.

10.4.3.2 Continuous State Monitoring

In addition to being protected from direct writes, the contents of the RPINRx and RPORx registers are constantly monitored in hardware by shadow registers. If an unexpected change in any of the registers occurs (such as cell disturbances caused by ESD or other external events), a configuration mismatch Reset will be triggered.

10.4.3.3 Configuration Bit Pin Select Lock

As an additional level of safety, the device can be configured to prevent more than one write session to the RPINRx and RPORx registers. The IOL1WAY (FOSC<IOL1WAY>) configuration bit blocks the IOLOCK bit from being cleared after it has been set once. If IOLOCK remains set, the register unlock procedure will not execute, and the peripheral pin select control registers cannot be written to. The only way to clear the bit and re-enable peripheral remapping is to perform a device Reset.

In the default (unprogrammed) state, IOL1WAY is set, restricting users to one write session. Programming IOL1WAY allows user applications unlimited access (with the proper use of the unlock sequence) to the peripheral pin select registers.

10.5 Peripheral Pin Select Registers

The dsPIC33FJ12MC201/202 family of devices implement 21 registers for remappable peripheral configuration:

- Input Remappable Peripheral Registers (13)
- Output Remappable Peripheral Registers (8)

Note: Input and Output Register values can only be changed if OSCCON<IOLOCK> = 0. See **Section 10.4.3.1 "Control Register Lock"** for a specific command sequence.

REGISTER 10-4: RPINR7: PERIPHERAL PIN SELECT INPUT REGISTER 7

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	IC2R<4:0>				
bit 15							bit 8

U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	—	IC1R<4:0>				
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

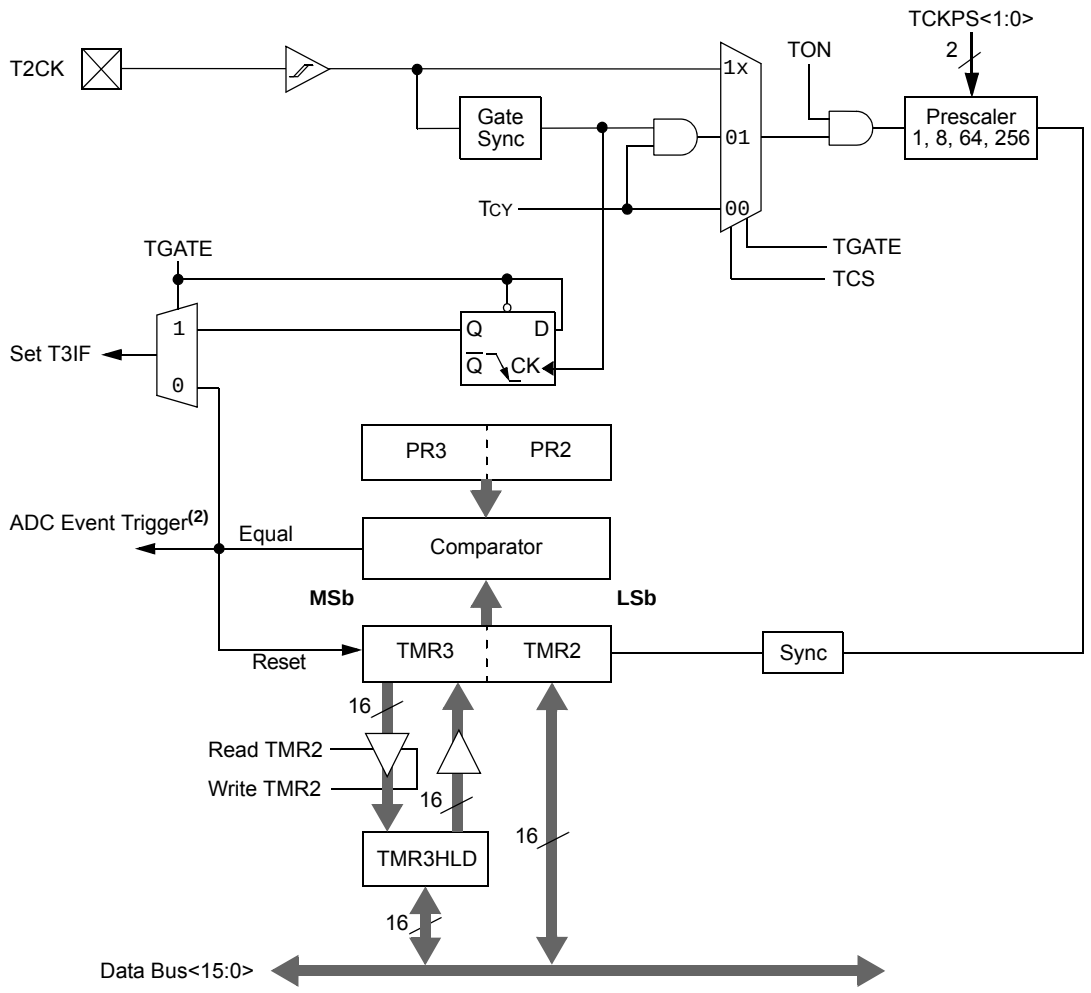
bit 15-13 **Unimplemented:** Read as '0'

bit 12-8 **IC2R<4:0>:** Assign Input Capture 2 (IC2) to the corresponding RPn pin
11111 = Input tied Vss
01111 = Input tied to RP15
.
.
.
00001 = Input tied to RP1
00000 = Input tied to RP0

bit 7-5 **Unimplemented:** Read as '0'

bit 4-0 **IC1R<4:0>:** Assign Input Capture 1 (IC1) to the corresponding RPn pin
11111 = Input tied Vss
01111 = Input tied to RP15
.
.
.
00001 = Input tied to RP1
00000 = Input tied to RP0

FIGURE 12-1: TIMER2/3 (32-BIT) BLOCK DIAGRAM(1)



Note 1: The 32-bit timer control bit, T32, must be set for 32-bit timer/counter operation. All control bits are respective to the T2CON register.

2: The ADC event trigger is available only on Timer2/3.

REGISTER 15-1: PxTCON: PWM TIME BASE CONTROL REGISTER

R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
PTEN	—	PTSIDL	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
PTOPS<3:0>				PTCKPS<1:0>		PTMOD<1:0>	
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **PTEN:** PWM Time Base Timer Enable bit
1 = PWM time base is on
0 = PWM time base is off

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **PTSIDL:** PWM Time Base Stop in Idle Mode bit
1 = PWM time base halts in CPU Idle mode
0 = PWM time base runs in CPU Idle mode

bit 12-8 **Unimplemented:** Read as ‘0’

bit 7-4 **PTOPS<3:0>:** PWM Time Base Output Postscale Select bits
1111 = 1:16 postscale
•
•
•
0001 = 1:2 postscale
0000 = 1:1 postscale

bit 3-2 **PTCKPS<1:0>:** PWM Time Base Input Clock Prescale Select bits
11 = PWM time base input clock period is 64 TCY (1:64 prescale)
10 = PWM time base input clock period is 16 TCY (1:16 prescale)
01 = PWM time base input clock period is 4 TCY (1:4 prescale)
00 = PWM time base input clock period is TCY (1:1 prescale)

bit 1-0 **PTMOD<1:0>:** PWM Time Base Mode Select bits
11 = PWM time base operates in a Continuous Up/Down Count mode with interrupts for double PWM updates
10 = PWM time base operates in a Continuous Up/Down Count mode
01 = PWM time base operates in Single Pulse mode
00 = PWM time base operates in a Free-Running mode

REGISTER 15-4: PxSECMP: SPECIAL EVENT COMPARE REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SEVTDIR(1)	SEVTCMP<14:8>(2)						
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SEVTCMP<7:0>(2)							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **SEVTDIR:** Special Event Trigger Time Base Direction bit(1)
1 = A Special Event Trigger will occur when the PWM time base is counting down
0 = A Special Event Trigger will occur when the PWM time base is counting up

bit 14-0 **SEVTCMP<14:0>:** Special Event Compare Value bits(2)

Note 1: SEVTDIR is compared with PTDIR (PxTMR<15>) to generate the Special Event Trigger.
2: PxSECMP<14:0> is compared with PxTMR<14:0> to generate the Special Event Trigger.

TABLE 24-6: DC CHARACTERISTICS: IDLE CURRENT (IIDLE)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Parameter No.	**Typical(1)**	**Max**	**Units**	**Conditions**		
Idle Current (IIDLE): Core OFF Clock ON Base Current(2)						
DC40d	3	25	mA	-40°C	3.3V	10 MIPS(3)
DC40a	3	25	mA	+25°C		
DC40b	3	25	mA	+85°C		
DC40c	3	25	mA	+125°C		
DC41d	4	25	mA	-40°C	3.3V	16 MIPS(3)
DC41a	4	25	mA	+25°C		
DC41b	5	25	mA	+85°C		
DC41c	5	25	mA	+125°C		
DC42d	6	25	mA	-40°C	3.3V	20 MIPS(3)
DC42a	6	25	mA	+25°C		
DC42b	7	25	mA	+85°C		
DC42c	7	25	mA	+125°C		
DC43a	9	25	mA	+25°C	3.3V	30 MIPS(3)
DC43d	9	25	mA	-40°C		
DC43b	9	25	mA	+85°C		
DC43c	9	25	mA	+125°C		
DC44d	10	25	mA	-40°C	3.3V	40 MIPS
DC44a	10	25	mA	+25°C		
DC44b	10	25	mA	+85°C		
DC44c	10	25	mA	+125°C		

Note 1: Data in “Typical” column is at 3.3V, 25°C unless otherwise stated.

2: Base IIDLE current is measured with core off, clock on and all modules turned off. Peripheral Module Disable SFR registers are zeroed. All I/O pins are configured as inputs and pulled to VSS.

3: These parameters are characterized, but not tested in manufacturing.

TABLE 24-10: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
	VOL	**Output Low Voltage**					
DO10		I/O ports	—	—	0.4	V	IOL = 2 mA, VDD = 3.3V
DO16		OSC2/CLKO	—	—	0.4	V	IOL = 2 mA, VDD = 3.3V
	VOH	**Output High Voltage**					
DO20		I/O ports	2.40	—	—	V	IOH = -2.3 mA, VDD = 3.3V
DO26		OSC2/CLKO	2.41	—	—	V	IOH = -1.3 mA, VDD = 3.3V

TABLE 24-11: ELECTRICAL CHARACTERISTICS: BOR

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min(1)**	**Typ**	**Max(1)**	**Units**	**Conditions**
BO10	VBOR	BOR Event on VDD transition high-to-low	2.40	—	2.55	V	VDD

Note 1: Parameters are for design guidance only and are not tested in manufacturing.

TABLE 24-40: I2Cx BUS DATA TIMING REQUIREMENTS (MASTER MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param No.	**Symbol**	**Characteristic(3)**		**Min(1)**	**Max**	**Units**	**Conditions**
IM10	TLO:SCL	Clock Low Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	—
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	—
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	—
IM11	THI:SCL	Clock High Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	—
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	—
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	—
IM20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(2)	—	100	ns	
IM21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(2)	—	300	ns	
IM25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	—
			400 kHz mode	100	—	ns	
			1 MHz mode(2)	40	—	ns	
IM26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	µs	—
			400 kHz mode	0	0.9	µs	
			1 MHz mode(2)	0.2	—	µs	
IM30	TSU:STA	Start Condition Setup Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM31	THD:STA	Start Condition Hold Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	After this period the first clock pulse is generated
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM33	TSU:STO	Stop Condition Setup Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	—
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM34	THD:STO	Stop Condition Hold Time	100 kHz mode	TCY/2 (BRG + 1)	—	ns	—
			400 kHz mode	TCY/2 (BRG + 1)	—	ns	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	ns	
IM40	TAA:SCL	Output Valid From Clock	100 kHz mode	—	3500	ns	—
			400 kHz mode	—	1000	ns	—
			1 MHz mode(2)	—	400	ns	—
IM45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	µs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
			1 MHz mode(2)	0.5	—	µs	
IM50	CB	Bus Capacitive Loading		—	400	pF	—
IM51	PGD	Pulse Gobbler Delay		65	390	ns	See **Note 4**

Note 1: BRG is the value of the I^2C Baud Rate Generator. Refer to **Section 19. "Inter-Integrated Circuit (I^2C™)"** (DS70195) in the "*dsPIC33F/PIC24H Family Reference Manual*". Please see the Microchip web site (www.microchip.com) for the latest family reference manual sections.

2: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

3: These parameters are characterized by similarity, but are not tested in manufacturing.

4: Typical value for this parameter is 130 ns.

TABLE 24-41: I2Cx BUS DATA TIMING REQUIREMENTS (SLAVE MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Param.	**Symbol**	**Characteristic(2)**		**Min**	**Max**	**Units**	**Conditions**
IS10	TLO:SCL	Clock Low Time	100 kHz mode	4.7	—	µs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	1.3	—	µs	Device must operate at a minimum of 10 MHz
			1 MHz mode(1)	0.5	—	µs	—
IS11	THI:SCL	Clock High Time	100 kHz mode	4.0	—	µs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	0.6	—	µs	Device must operate at a minimum of 10 MHz
			1 MHz mode(1)	0.5	—	µs	—
IS20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(1)	—	100	ns	
IS21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(1)	—	300	ns	
IS25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	—
			400 kHz mode	100	—	ns	
			1 MHz mode(1)	100	—	ns	
IS26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	µs	—
			400 kHz mode	0	0.9	µs	
			1 MHz mode(1)	0	0.3	µs	
IS30	TSU:STA	Start Condition Setup Time	100 kHz mode	4.7	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	0.6	—	µs	
			1 MHz mode(1)	0.25	—	µs	
IS31	THD:STA	Start Condition Hold Time	100 kHz mode	4.0	—	µs	After this period, the first clock pulse is generated
			400 kHz mode	0.6	—	µs	
			1 MHz mode(1)	0.25	—	µs	
IS33	TSU:STO	Stop Condition Setup Time	100 kHz mode	4.7	—	µs	—
			400 kHz mode	0.6	—	µs	
			1 MHz mode(1)	0.6	—	µs	
IS34	THD:STO	Stop Condition Hold Time	100 kHz mode	4000	—	ns	—
			400 kHz mode	600	—	ns	
			1 MHz mode(1)	250		ns	
IS40	TAA:SCL	Output Valid From Clock	100 kHz mode	0	3500	ns	—
			400 kHz mode	0	1000	ns	
			1 MHz mode(1)	0	350	ns	
IS45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	µs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	µs	
			1 MHz mode(1)	0.5	—	µs	
IS50	CB	Bus Capacitive Loading		—	400	pF	—

Note 1: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

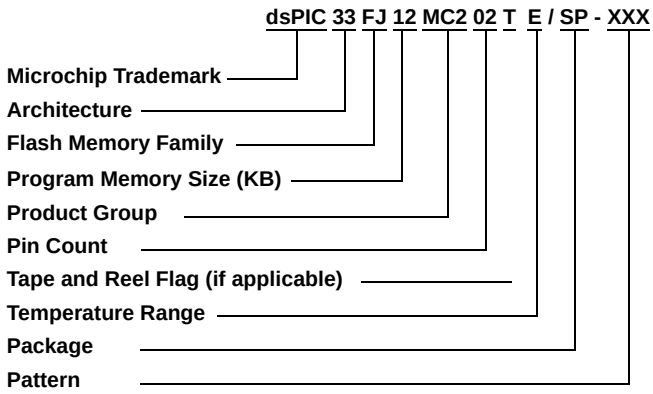
2: These parameters are characterized by similarity, but are not tested in manufacturing.

TABLE 25-1: MAJOR SECTION UPDATES

Section Name	Update Description
Section 19.0 "10-bit/12-bit Analog-to-Digital Converter (ADC)"	Updated ADC Conversion Clock Select bits in the AD1CON3 register from ADCS<**5**:0> to ADCS<**7**:0>. Any references to these bits have also been updated throughout this data sheet (Register 19-3). Replaced Figure 19-1 (ADC1 Module Block Diagram for dsPIC33FJ12MC201) and added Figure 19-2 (ADC1 Block Diagram for dsPIC33FJ12MC202). Removed Equation 19-1: ADC Conversion Clock Period and Figure 19-2: ADC Transfer Function (10-Bit Example). Added Note 2 to Figure 19-2: ADC Conversion Clock Period Block Diagram. Updated ADC1 Input Channel 1, 2, 3 Select Register (see Register 19-4) as follows: • Changed bit 10-9 (CH123NB - dsPIC33FJ12MC201 devices only) description for bit value of `10` (if AD12B = `0`). • Updated bit 8 (CH123SB) to reflect device-specific information. • Updated bit 0 (CH123SA) to reflect device-specific information. • Changed bit 2-1 (CH123NA - dsPIC33FJ12MC201 devices only) description for bit value of `10` (if AD12B = `0`). Updated ADC1 Input Channel 0 Select Register (see Register 19-5) as follows: • Changed bit value descriptions for bits 12-8 • Changed bit value descriptions for bits 4-0 (dsPIC33FJ12MC201 devices) Modified Notes 1 and 2 in the ADC1 Input Scan Select Register Low (see Register 19-6) Modified Notes 1 and 2 in the ADC1 Port Configuration Register Low (see Register 19-7)
Section 20.0 "Special Features"	Added FICD register information for address 0xF8000E in the Device Configuration Register Map (see Table 20-1). Added FICD register content (BKBUG, COE, JTAGEN, and ICS<1:0> to the dsPIC33FJ12MC201/202 Configuration Bits Description (see Table 20-2). Added a note regarding the placement of low-ESR capacitors, after the second paragraph of **Section 20.2 "On-Chip Voltage Regulator"** and to Figure 20-2. Removed the words "if enabled" from the second sentence in the fifth paragraph of **Section 20.3 "BOR: Brown-out Reset"**

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.



Architecture:	33	=	16-bit Digital Signal Controller
Flash Memory Family:	FJ	=	Flash program memory, 3.3V
Product Group:	MC2	=	Motor Control family
Pin Count:	01	=	20-pin
	02	=	28-pin
Temperature Range:	I	=	-40° C to+85° C (Industrial)
	E	=	-40° C to+125° C (Extended)
Package:	P	=	Plastic Dual In-Line - 300 mil body (PDIP)
	SP	=	Skinny Plastic Dual In-Line - 300 mil body (SPDIP)
	SO	=	Plastic Small Outline - Wide, 7.50 mil body (SOIC)
	ML	=	Plastic Quad, No Lead Package - 6x6 mm body (QFN)
	SS	=	Plastic Shrink Small Outline - 5.3 mm body (SSOP)

Examples:

a) dsPIC33FJ12MC202-E/SP:
Motor Control dsPIC33, 12 KB program memory, 28-pin, Extended temperature, SPDIP package.